Unit: mm

DB2S310

Silicon epitaxial planar type

For high speed switching circuits DB2J310 in SSMini2 type package

■ Features

- \bullet Low forward voltage V_{F}
- Short reverse recovery time t_{rr}
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

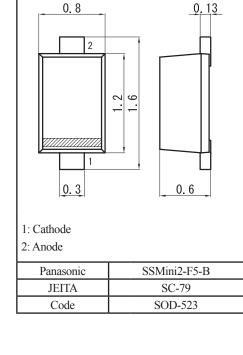
■ Marking Symbol: B7

■ Packaging

 $DB2S31000L \quad Embossed \ type \ (Thermo-compression \ sealing): \ 3\,000 \ pcs \ / \ reel \ (standard)$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	30	V	
Repetitive peak reverse voltage	V _{RRM}	30	V	
Forward current (Average)	I _{F(AV)}	200	mA	
Peak forward current	I_{FM}	300	mA	
Non-repetitive peak forward surge current *1	I_{FSM}	1	A	
Junction temperature	T_j	125	°C	
Operating ambient temperature	T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C	



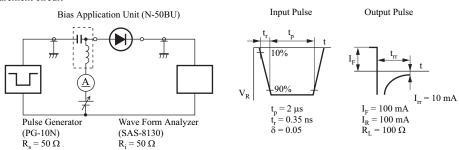
Note) *1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25$ °C±3°C

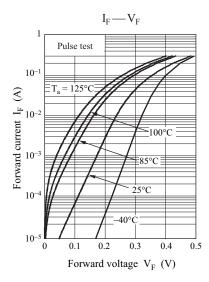
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 200 \text{ mA}$			0.47	V
Reverse current	I _{R1}	$V_R = 10 V$			20	μΑ
	I_{R2}	$V_R = 30 \text{ V}$			200	
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		4.5		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		1.6		ns

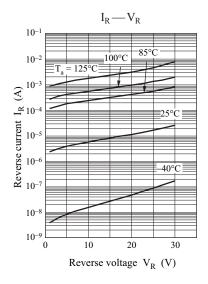
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

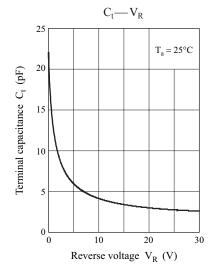
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 \mbox{MHz}
 - *1: t_{rr} measurement circuit



DB2S310 Panasonic

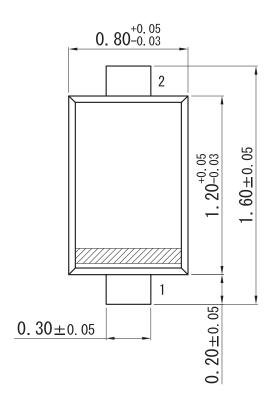


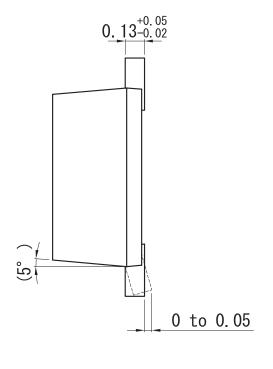


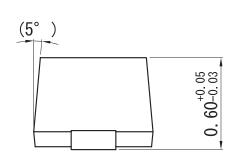


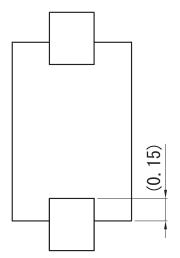
SSMini2-F5-B

Unit: mm

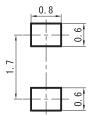








■ Land Pattern (Reference) (Unit: mm)



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